ASSOCIATION CONNECTING	Material Composit © Copyright 2005. IPC, * international and Pan-Ar	Bannockb	urn, Illinois. A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declaration	ion of the s encompasse	ubstances es all lower	within the manufactu r level materials for w	rer listed i hich the n	tem. Note: i nanufacture	if the item is an as r has engineering	sembly with lower responsibility.	
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type   http://www.ipc.org/IPC-175x Distribute				*	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information				
Supplier Informa	ation														
Company name*			Company unique ID				Unique ID Authority					Response Date*			
onsemi											2024-05-16				
Contact Name			Title - Contact				Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative				Phone - Representative*			Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester	Requester Item Number Mfr Iten		n Number Mfr Item Name				Effective Date	e Version	N	Manufacturing Site		Weight*	UOM	Unit Type	
		NCV887701D1R2G Auto S		Auto Start-Stop E	Auto Start-Stop Boost		2024-05-16		F	PH1		72.0	mg	Each	
Manufacturing P	Proccess Information	1													
Terminal Plating / Grid Array Material Term			erminal Base Alloy J-STD-020 MSL Rat			L Rating	Peak Process Body Temperature Max Time at Peak			Temperature Number of Reflow Cycles					
Matte Tin (Sn) - annealed CU Allo			CU Alloy		1		260		С	30	secon	ids 3			
Comments															
evel 1 - maximum tir	me at peak temperature o	luring sol	dering is 10-3	0 seconds											
For more information	n regarding material con	position	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

				ance category (JIG or Requester) or enter a [F] Optionally enter the positive (+) and n				
sigma range of distribution unless	s otherwise noted).	it of the substance of the f		[1] Optionally enter the positive (1) and h	egative () toterance in per	cent (110te: percer	n tolerance varies are	
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.33	mg	Supplier	Silicon (Si)	7440-21-3		1.33	mg
Die Attach	2.4	mg	Supplier	Silver (Ag)	7440-22-4		1.8	mg
			Supplier	Epoxy resins	129915-35-1		0.6	mg
Lead Frame	37.61	mg	Supplier	Silver (Ag)	7440-22-4		0.7898	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0752	mg
			Supplier	Iron (Fe)	7439-89-6		0.9403	mg
			Supplier	Copper (Cu)	7440-50-8		35.8047	mg
Mold Compound-Black	28.58	mg		Epoxy resin	proprietary data		1.429	mg
			Supplier	Phenolic Resin	Proprietary Data		1.429	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.5716	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1429	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.0075	mg
Plating	1.89	mg	Supplier	Tin (Sn)	7440-31-5		1.89	mg
Wire Bond - Au	0.19	mg	Supplier	Gold (Au)	7440-57-5		0.19	mg